AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A crosslinkable elastomer composition which comprises a crosslinkable elastomer component and a metal oxide filler containing a silicon oxide filler in an amount of not less than 60 % by weight of said metal oxide filler; said silicon oxide filler has a content of impurity metals other than silicon of not more than 100 ppm which is measured under the following conditions:

(i) the silicon oxide filler is dispersed and dissolved in 50% hydrofluoric acid and is diluted with ultrapure water; and

(ii) contents of metals of the solution are determined through atomic absorption analysis by using an atomic absorption photometer.

2. (original): The crosslinkable elastomer composition of Claim 1, wherein said metal oxide filler consists of the silicon oxide filler.

3. (previously presented): The crosslinkable elastomer composition of Claim 1, wherein said silicon oxide filler has quartz crystal structure.

4. (previously presented): The crosslinkable elastomer composition of Claim 1, wherein said silicon oxide filler is blended in an amount of from 1 to 150 parts by weight on the basis of 100 parts by weight of the elastomer component.

5. (previously presented): The crosslinkable elastomer composition of Claim 1, which contains a crosslinking agent and said silicon oxide filler in amounts of 0.05 to 10 parts by weight and 1 to 150 parts by weight, respectively on the basis of 100 parts by weight of the elastomer component.

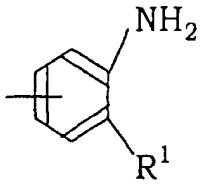
6. (previously presented): The crosslinkable elastomer composition of Claim 1, wherein the elastomer component is a fluorine-containing elastomer.

7. (original): The crosslinkable elastomer composition of Claim 6, wherein the elastomer component is a fluorine-containing elastomer capable of being crosslinked with a peroxide crosslinking agent.

8. (original): The crosslinkable elastomer composition of Claim 6, wherein the elastomer component is a fluorine-containing elastomer capable of being crosslinked with an imidazole, oxazole, thiazole or triazine crosslinking agent.

9. (previously presented): The crosslinkable elastomer composition of Claim 6, wherein the crosslinking agent is an organic peroxide.

10. (currently amended): The crosslinkable elastomer composition of ~~Claim 6~~ Claim 5, wherein the crosslinking agent is a compound having at least two functional groups represented by the formula (I):



wherein R^1 is any one of OH, NH_2 or SH.

11. (previously presented): A molded article obtained by crosslinking the elastomer composition of Claim 1.

12. (currently amended): The molded article of Claim 11, wherein ~~an increasing rate of particles generated by irradiating oxygen plasma to the article~~ an increase in particle generation rate of the molded article prior to and following irradiation of the molded article with oxygen plasma is not more 1,000%,

said particle generation rate determined by measuring the number of particles having a particle size of not less than 0.2 μm released per unit area of the molded article upon washing with a supersonic wave in ultrapure water at 25°C for one hour.

13. (original): The molded article of Claim 11, wherein an amount of impurity metals other than silicon which are extracted with a 50 % aqueous solution of HF is not more than 200 ppb.

14. (original): The molded article of Claim 11, which contains impurity metals other than silicon in an amount of not more than 100 ppm.

15. (currently amended): The molded article of Claim 11, wherein the article is ~~used for~~ a component of a semiconductor manufacturing equipment.

16. (original): The molded article of Claim 15, wherein the article is a sealing member used for sealing of a semiconductor manufacturing equipment.

17. (original): The molded article of Claim 13, wherein the article is a sealing member used for sealing of a semiconductor manufacturing equipment for wet process.

18. (original): The molded article of Claim 17, wherein the article is a sealing member used for sealing of a semiconductor manufacturing equipment for a process with ultrapure water.